**Features :**

- Isolated mounting base 2500V~
- Pressure contact technology with Increased power cycling capability
- Space and weight saving

Typical Applications

- Welding

SYMBOL	CHARACTERISTIC	TEST CONDITIONS	T _j (°C)	VALUE			UNIT
				Min	Type	Max	
I _{T(RMS)}	RMS on-state current	The two chips are assembled in reverse parallel and are continuous on current. T _{water} =30°C, 5L/min				690	A
		The two chips are assembled in reverse parallel ,usage rate 10%, twenty flowing on current continuously. T _{water} =30°C, 5L/min				960	A
V _{DRM} /V _{RPM}	Repetitive peak off-state voltage Repetitive peak reverse voltage	tp=10ms	125			1600	V
I _{DRM} /I _{RPM}	Repetitive peak current	at V _{DRM} at V _{RPM}	125			35	mA
I _{TSM}	Surge on-state current	10ms half sine wave	125			11	kA
I ² t	I ² t for fusing coordination	V _R =60%V _{RPM}				605	10 ³ A ² s
V _{TO}	Threshold voltage		125			0.80	V
r _T	On-state slope resistance					0.80	mΩ
V _{TM}	Peak on-state voltage	I _{TM} =1200A	25			1.90	V
dv/dt	Critical rate of rise of off-state voltage	V _{DM} =67%V _{DRM}	125			800	V/μs
di/dt	Critical rate of rise of on-state current	Gate source 1.5A, t _r ≤0.5μs Repetitive	125			100	A/μs
I _{GT}	Gate trigger current	V _A =12V, I _A =1A	25	30		200	mA
V _{GT}	Gate trigger voltage			1.0		3.0	V
I _H	Holding current			20		200	mA
V _{GD}	Non-trigger gate voltage	V _{DM} =67%V _{DRM}	125	0.2			V
I _{GD}	Non-trigger gate current	V _{DM} =67%V _{DRM}	125	1.5			mA
R _{th(j-c)}	Thermal resistance Junction to case	Single side cooled. per chip. DC				0.110	°C/W
R _{th(c-w)}	Thermal resistance case to water	Single side cooled. per chip. (5L/min)				0.056	°C/W
V _{iso}	Isolation voltage	50Hz, R.M.S, t=1min, I _{iso} : 1mA(Max)		2500			V
F _m	Terminal connection torque(M8)			8.0		12.0	N·m
	Mounting torque(M6)			4.5		6.0	N·m
T _{vj}	Junction temperature			-40		125	°C
T _{stg}	Stored temperature			-40		125	°C
T _{water}	Water temperature	Water flow=5L/min				30	°C
-	Water Pressure loss					21	kPa
W _t	Weight					1340	g
Outline	M13						

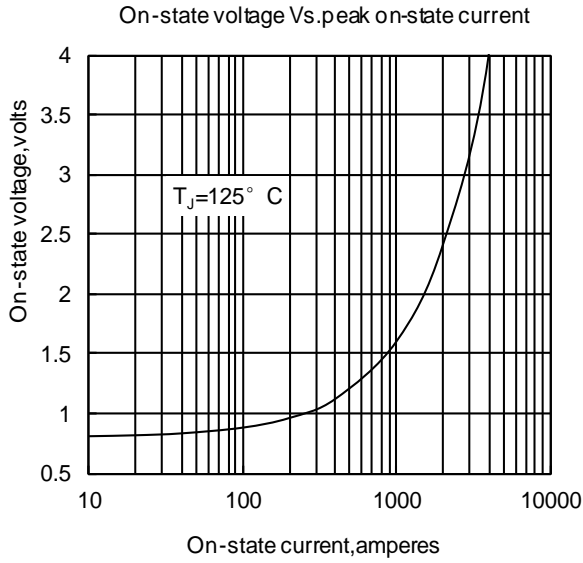


Fig1

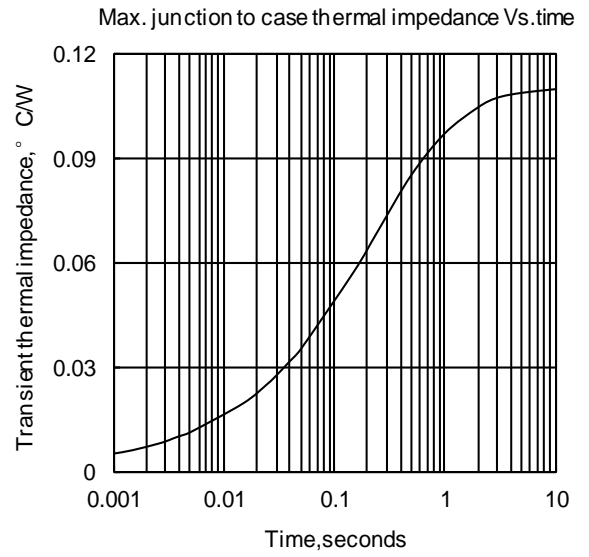


Fig2

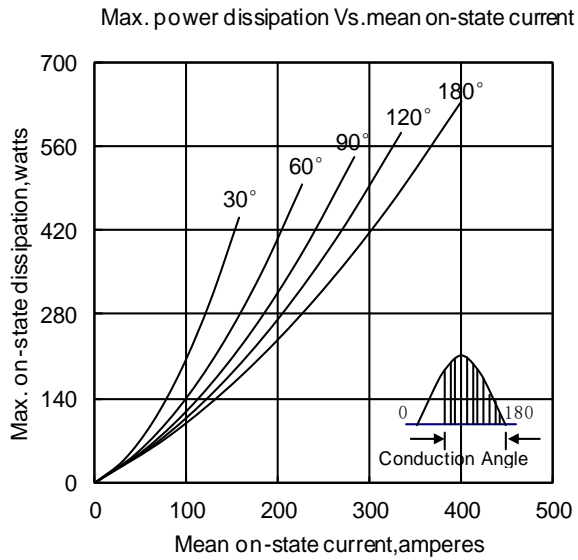


Fig3

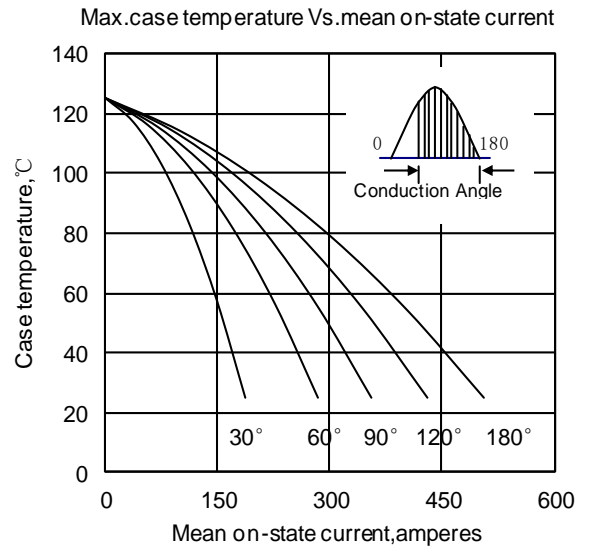


Fig4

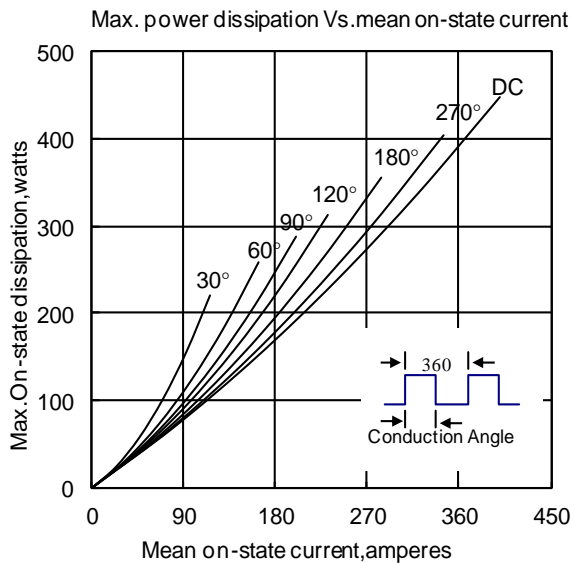


Fig5

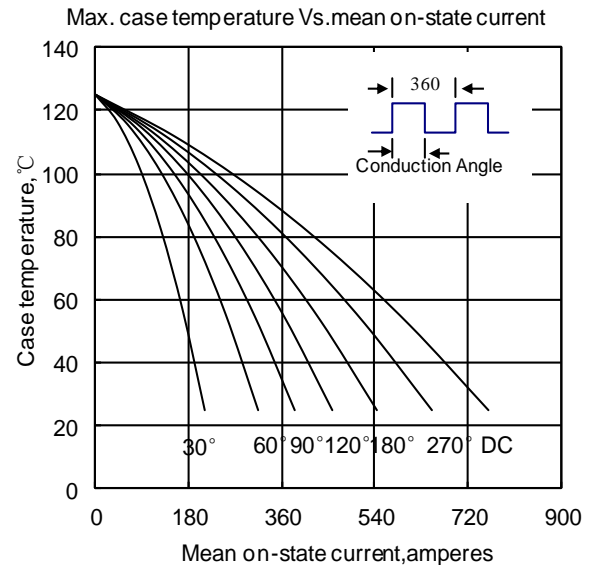


Fig6

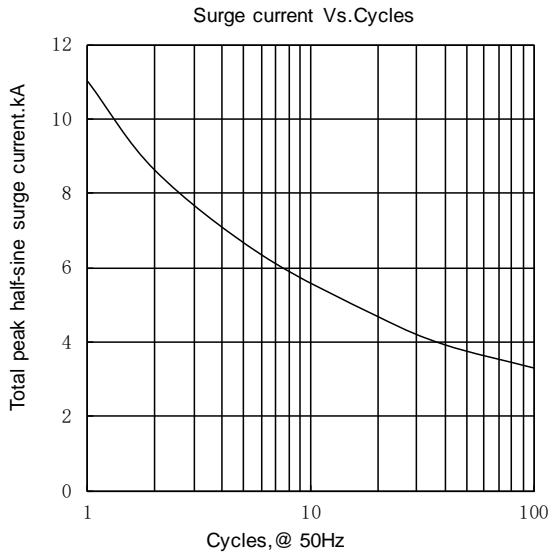


Fig.7

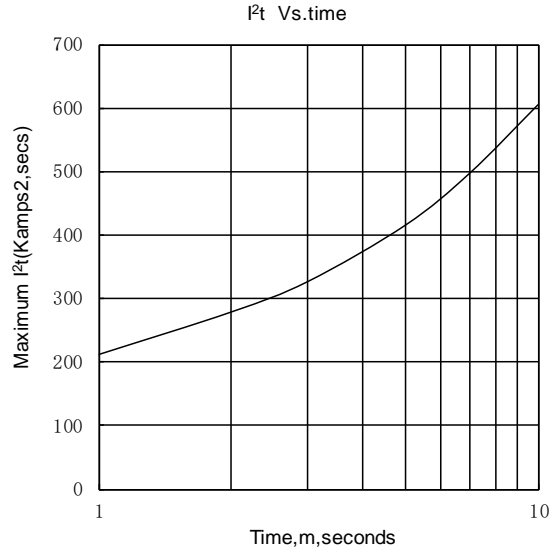


Fig.8

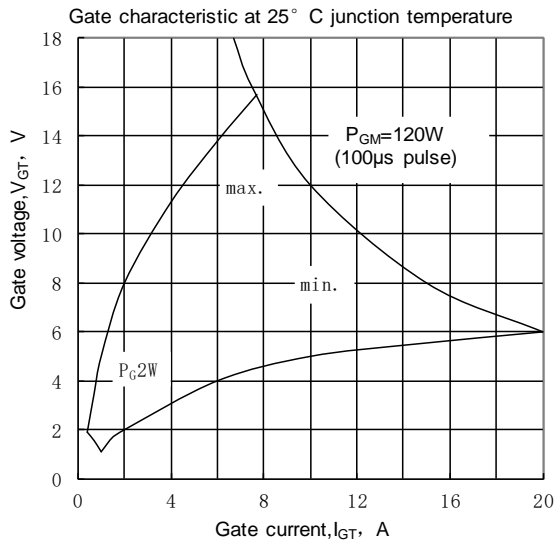


Fig.9

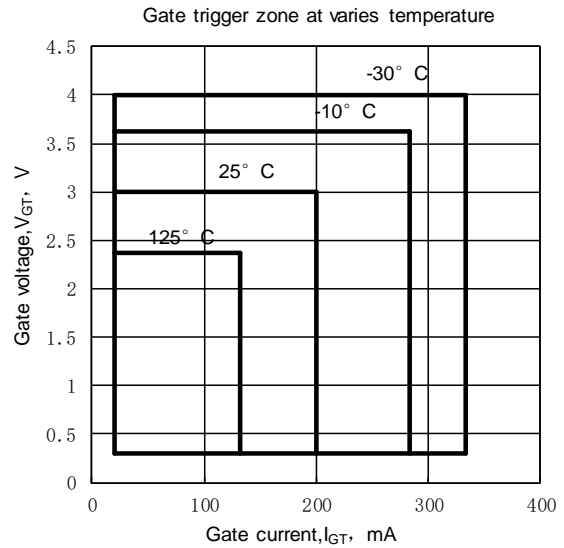


Fig.10

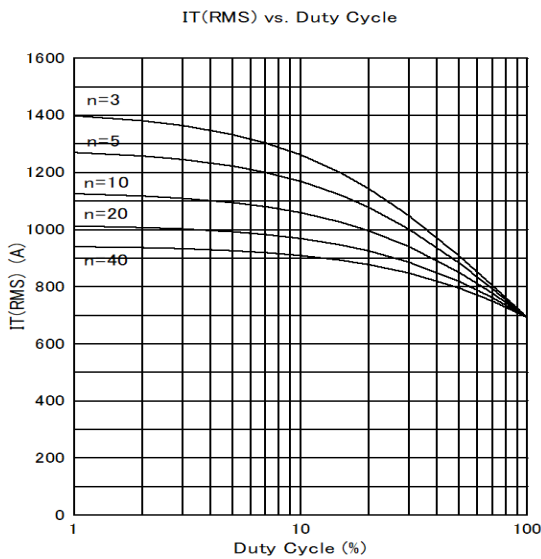


Fig.11

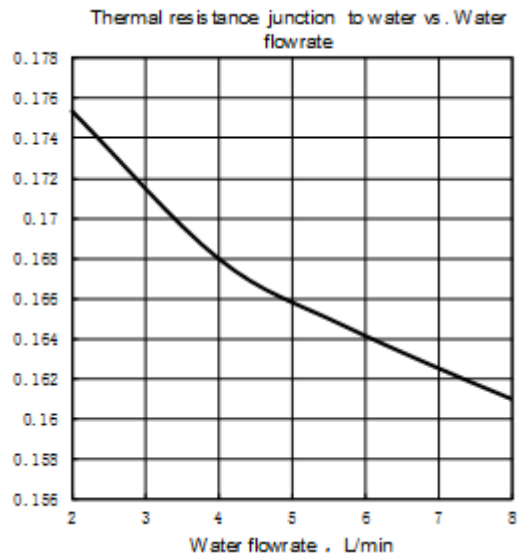


Fig.12

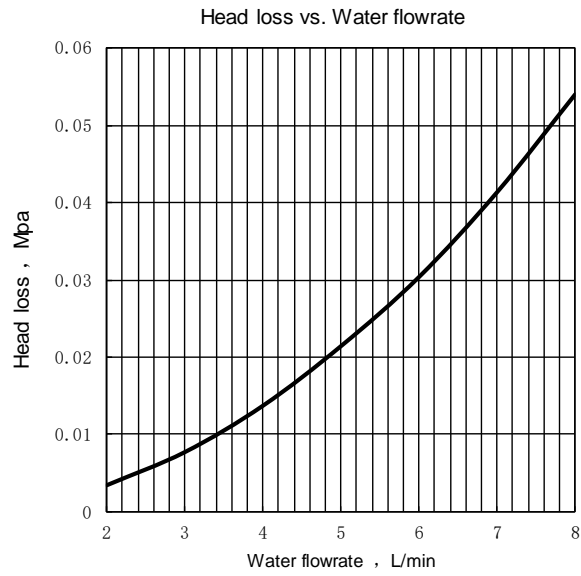
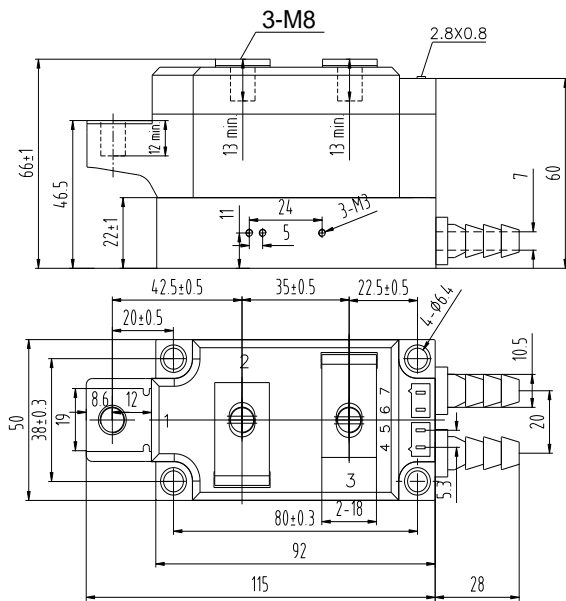


Fig.13



MD400T160W

